

Four-channel Power/Energy IC

Features

- Energy Linearity: ±0.1% of Reading over 1000:1 Dynamic Range
- On-chip Functions:
 - Voltage and Current Measurement
 - Active, Reactive, and Apparent Power/Energy
 - RMS Voltage and Current Calculations
 - Current Fault and Voltage Sag Detection
 - Calibration
 - Phase Compensation
 - Temperature Sensor
 - Energy Pulse Outputs
- Meets Accuracy Spec for IEC, ANSI, & JIS
- Low Power Consumption
- Voltage Tamper Correction
- Ground-referenced Inputs with Single Supply
- On-chip 2.5 V Reference (40 ppm / °C typ.)
- Power Supply Monitor Function
- Three-wire Serial Interface to Microcontroller or E²PROM
- Power Supply Configurations GND: 0 V, VA+: +5 V, VD+: +3.3 V to +5 V

Description

The CS5467 is a watt-hour meter on a chip. It measures line voltage and current and calculates active, reactive, apparent power, energy, power factor, and RMS voltage and current.

An internal RMS voltage reference can be used if voltage measurement is disabled by tampering.

Four $\Delta\Sigma$ analog-to-digital converters are used to measure two voltages and two currents. Optionally, voltage2 channel can be used for temperature measurement.

The CS5467 is designed to interface to a variety of voltage and current sensors.

Additional features include system-level calibration, voltage sag and current fault detection, peak detection, phase compensation, and energy pulse outputs.

ORDERING INFORMATION See Page 45.

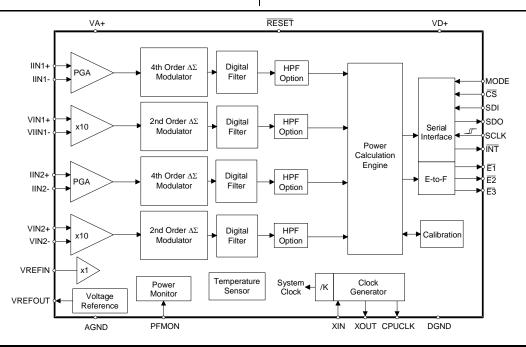




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1. OVERVIEW

The CS5467 is a CMOS power measurement integrated circuit utilizing four $\Delta\Sigma$ analog-to-digital converters to measure two line voltages and two currents. Optionally, voltage2 channel can be used for temperature measurement. It calculates active, reactive, and apparent power as well as RMS and peak voltage and current. It handles other system-related functions, such as pulse output conversion, voltage sag, current fault, voltage zero crossing, line frequency, and voltage tamper correction.

The CS5467 is optimized to interface to current transformers or shunt resistors for current measurement, and to resistive dividers or voltage transformers for voltage measurement. Two full-scale ranges are provided on the current inputs to accommodate both types of current sensors. The CS5467's four differential inputs have a common-mode input range from analog ground (AGND) to the positive analog supply (VA+).

An additional analog input (PFMON) is provided to allow the application to determine when a power failure is in progress. By monitoring the unregulated power supply, the application can take any required action when a power loss occurs.

An on-chip voltage reference (nominally 2.5 volts) is generated and provided at analog output, VREFOUT. This reference can be supplied to the chip by connecting it to the reference voltage input, VREFIN. Alternatively, an external voltage reference can be supplied to the reference input.

Three digital outputs ($\overline{E1}$, $\overline{E2}$, $\overline{E3}$) provide a variety of output signals and, depending on the mode selected, provide energy pulses, power failure indication, or other choices.

The CS5467 includes a three-wire serial host interface to an external microcontroller or serial E^2 PROM. Signals include serial data input (SDI), serial data output (SDO), serial clock (SCLK), and optionally a chip select (CS), which allows the CS5467 to share the SDO signal with other devices. A MODE input is used to control whether an E^2 PROM will be used instead of a host microcontroller.

2. PIN DESCRIPTION

			1 1	1		
Crystal Out	XOUT	╡1●	28		XIN	Crystal In
CPU Clock Output	CPUCLK	2	27	þ	SDI	Serial Data Input
Positive Digital Supply	VD+	3	26	þ	E2	Energy Output 2
Digital Ground	DGND	4	25	þ	Ē1	Energy Output 1
Serial Clock	SCLK	5	24	þ	INT	Interrupt
Serial Data Ouput	SDO (6	23	þ	RESET	Reset
Chip Select	CS I	7	22	þ	Ē3	Energy Output 3
Mode Select	MODE	8	21	þ	PFMON	Power Fail Monitor
Differential Voltage Input	VIN1+	9	20	þ	IIN1+	Differential Current Input
Differential Voltage Input	VIN1-	10	19	þ	IIN1-	Differential Current Input
Voltage Reference Output	VREFOUT	11	18	þ	VA+	Positive Analog Supply
Voltage Reference Input	VREFIN	12	17	þ	AGND	Analog Ground
Differential Voltage Input	VIN2+	13	16	þ	IIN2+	Differential Current Input
Differential Voltage Input	VIN2-	14	15	þ	IIN2-	Differential Current Input
				1		

Clock Generator		
Crystal Out Crystal In	1,28	XOUT, XIN — Connect to an external quartz crystal. Alternatively, an external clock can be supplied to the XIN pin to provide the system clock for the device.
CPU Clock Output	2	CPUCLK — Logic-level output from crystal oscillator. Can be used to clock an external CPU.
Control Pins and Serial Data	I/O	
Serial Clock	5	SCLK — Clocks serial data from the SDI pin and to the SDO pin when \overline{CS} is low. SCLK is a Schmitt-trigger input when MODE is low and a driven output when MODE is high.
Serial Data Output	6	SDO — Serial data output. Data is clocked out by SCLK.
Chip Select	7	CS — An input that enables the serial interface when MODE is low and a driven output when MODE is high.
Mode Select	8	MODE — High selects external E ² PROM, Low selects external microcontroller. MODE includes a weak internal pull-down and therefore selects microcontroller mode if not connected.
Energy Output	22, 25, 26	E3 , E1 , E2 — Primarily active-low energy pulse outputs. These can be programmed to output other conditions.
Reset	23	RESET — An active-low Schmitt-trigger input used to reset the chip.
Interrupt	24	INT — Active-low output, indicates that an enabled condition has occurred.
Serial Data Input	27	SDI — Serial data input. Data is clocked in by SCLK.
Analog Inputs/Outputs		
Differential Voltage Inputs	9,10 13, 14	VIN1+, VIN1-, VIN2+, VIN2- — Differential analog inputs for the voltage channels.
Differential Current Inputs	20,19, 16,15	IIN1+, IIN1-, IIN2+, IIN2- — Differential analog inputs for the current channels.
Voltage Reference Output	11	VREFOUT — The on-chip voltage reference output. Nominally 2.5 V, referenced to AGND.
Voltage Reference Input	12	VREFIN — The voltage reference input. Can be connected to VREFOUT or external 2.5 V reference.
Power Supply Connections		
Positive Digital Supply	3	VD+ — The positive digital supply.
Digital Ground	4	DGND — Digital ground.
Positive Analog Supply	18	VA+ — The positive analog supply.
Analog Ground	17	AGND — Analog ground.
Power Fail Monitor	21	PFMON — Used to monitor the unregulated power supply via a resistive divider. If the PFMON voltage drops below its low limit, the low-supply detect (LSD) bit is set in the <i>Status</i> register.

3. CHARACTERISTICS & SPECIFICATIONS

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Тур	Max	Unit
Positive Digital Power Supply	VD+	3.135	5.0	5.25	V
Positive Analog Power Supply	VA+	4.75	5.0	5.25	V
Voltage Reference	VREFIN	-	2.5	-	V
Specified Temperature Range	Τ _Α	-40	-	+85	°C

ANALOG CHARACTERISTICS

• Min / Max characteristics and specifications are guaranteed over all Recommended Operating Conditions.

• Typical characteristics and specifications are measured at nominal supply voltages and TA = 25 °C.

• VA+ = VD+ = 5 V \pm 5%; AGND = DGND = 0 V; VREFIN = +2.5 V. All voltages with respect to 0 V.

• DCLK = 4.096 MHz.

Param	neter	Symbol	Min	Тур	Max	Unit
Accuracy				•		
Active Power (Note 1)	All Gain Ranges Input Range 0.1% - 100%	P _{ACTIVE}	-	±0.1	-	%
Reactive Power (Note 1 and 2)	All Gain Ranges Input Range 0.1% - 100%	Q _{AVG}	-	±0.2	-	%
Power Factor (Note 1 and 2)	All Gain Ranges Input Range 1.0% - 100% Input Range 0.1% - 1.0%	PF	- -	±0.2 ±0.27	-	% %
Current RMS (Note 1)	All Gain Ranges Input Range 1.0% - 100% Input Range 0.1% - 1.0%	I _{RMS}	-	±0.1 ±0.17	-	% % %
Voltage RMS (Note 1)	All Gain Ranges Input Range 5% - 100%	V _{RMS}	-	±0.1	-	%
Analog Inputs (All Inputs)						
Common Mode Rejection	(DC, 50, 60 Hz)	CMRR	80	-	-	dB
Common Mode + Signal			-0.25	-	VA+	V
Analog Inputs (Current Inputs	5)					
Differential Input Range [(IIN+) – (IIN-)]	(Gain = 10) (Gain = 50)	IIN	-	500 100	-	mV _{P-P} mV _{P-P}
Total Harmonic Distortion	(Gain = 50)	THD	80	94	-	dB
Crosstalk from Voltage input at	Full Scale (50, 60 Hz)		-	-115	-	dB
Input Capacitance		IC	-	27	-	pF
Effective Input Impedance		EII	30	-	-	kΩ
Noise (Referred to Input)	(Gain = 10) (Gain = 50)	NI	-		22.5 4.5	μV _{rms} μV _{rms}
Offset Drift (Without the High-pa	ass Filter)	OD	-	4.0	-	μV/°C
Gain Error	(Note 3)	GE	-	±0.4		%

Notes: 1. Applies when the HPF option is enabled.

2. Applies when the line frequency is equal to the product of the output word rate (OWR) and the value of *Epsilon*.

ANALOG CHARACTERISTICS (Continued)

Parameter	Symbol	Min	Тур	Max	Unit
Analog Inputs (Voltage Inputs)	-				
Differential Input Range [(VIN+) – (VIN-)]	VIN	-	500	-	mV _{P-P}
Total Harmonic Distortion	THD	65	75	-	dB
Crosstalk from Current inputs at Full Scale (50, 60 Hz)		-	-70	-	dB
Input Capacitance All Gain Ranges	IC	-	2.0	-	pF
Effective Input Impedance	EII	2	-	-	MΩ
Noise (Referred to Input)	N _V	-	-	140	μV _{rms}
Offset Drift (Without the High-pass Filter)	OD	-	16.0	-	µV/°C
Gain Error (Note 3)	GE	-	±3.0		%
Temperature					
Temperature Accuracy	Т	-	±5	-	°C
Power Supplies					
Power Supply Currents (Active State)	PSCA	-	1.5	-	mA
$I_{D+} (VA+ = VD+ = 5 V)$	PSCD	-	3.5	-	mA
I_{D+} (VA+ = 5 V, VD+ = 3.3 V)	PSCD	-	2.3	-	mA
Power Consumption Active State (VA+ = VD+ = 5 V)		-	25	33	mW
(Note 4) Active State $(VA + = 5 V, VD + = 3.3 V)$	PC	-	15	20	mW
Stand-by State	10	-	7	-	mW
Sleep State		-	10	-	uW
Power Supply Rejection Ratio (50, 60 Hz)					
(Note 5) Voltage	PSRR	48	55	-	dB
Current (Gain = 50x)		68	75	-	dB
Current (Gain = 10x)		60	65	-	dB
PFMON Low-voltage Trigger Threshold (Note 6)	PMLO	2.3	2.45	-	V
PFMON High-voltage Power-on Trip Point (Note 7)	PMHI	-	2.55	2.7	V

Notes: 3. Applies before system calibration.

4. All outputs unloaded. All inputs CMOS level.

5. Measurement method for PSRR: VREFIN tied to VREFOUT, VA+ = VD+ = 5 V, a 150 mV (zero-to-peak) (60 Hz) sinewave is imposed onto the +5 V DC supply voltage at VA+ and VD+ pins. The "+" and "-" input pins of both input channels are shorted to AGND. The CS5467 is then commanded to continuous conversion acquisition mode, and digital output data is collected for the channel under test. The (zero-to-peak) value of the digital sinusoidal output signal is determined, and this value is converted into the (zero-to-peak) value of the sinusoidal voltage (measured in mV) that would need to be applied at the channel's inputs, in order to cause the same digital sinusoidal output. This voltage is then defined as Veq. PSRR is (in dB):

$$\mathsf{PSRR} = 20 \cdot \mathsf{log} \left[\frac{150}{\mathsf{V}_{\mathsf{eq}}} \right]$$

- 6. When the voltage level on PFMON is sagging and LSD bit = 0, this is the voltage at which LSD is set to 1.
- 7. If the LSD bit has been set to 1 (because PFMON voltage fell below PMLO), this is the voltage level on PFMON at which the LSD bit can be permanently reset back to 0.



VOLTAGE REFERENCE

Parameter	Symbol	Min	Тур	Max	Unit
Reference Output					•
Output Voltage	VREFOUT	+2.4	+2.5	+2.6	V
Temperature Coefficient (Note 8)	TC _{VREF}	-	40	-	ppm/°C
Load Regulation (Note 9)	ΔV_R	-	6	10	mV
Reference Input	1			L	
Input Voltage Range	VREFIN	+2.4	+2.5	+2.6	V
Input Capacitance		-	4	-	pF
Input CVF Current		-	100	-	nA

Notes: 8. The voltage at VREFOUT is measured across the temperature range. From these measurements the following formula is used to calculate the VREFOUT temperature coefficient.

$$TC_{VREF} = \left(\frac{(VREFOUT_{MAX} - VREFOUT_{MIN})}{VREFOUT_{AVG}}\right) \left(\frac{1}{T_A MAX} - T_A MIN\right) \left(1.0 \times 10^6\right)$$

9. Specified at maximum recommended output of 1 μ A, source or sink.

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DIGITAL CHARACTERISTICS

- Min / Max characteristics and specifications are guaranteed over all Recommended Operating Conditions.
- Typical characteristics and specifications are measured at nominal supply voltages and TA = 25 $^{\circ}$ C.
- VA+ = VD+ = 5V \pm 5%; AGND = DGND = 0 V. All voltages with respect to 0 V.

• DCLK = 4.096 MHz.

Parameter	Symbol	Min	Тур	Max	Unit
Master Clock Characteristics			•		
Master Clock Frequency Internal Gate Oscillator (Note 11)	DCLK	2.5	4.096	20	MHz
Master Clock Duty Cycle		40	-	60	%
CPUCLK Duty Cycle (Note 12 and 13)	40	-	60	%
Filter Characteristics			•		
Phase Compensation Range (60 Hz, OWR = 4000 Hz)		-5.4	-	+5.4	0
Input Sampling Rate DCLK = MCLK/K		-	DCLK/8	-	Hz
Digital Filter Output Word Rate (Both channels)	OWR	-	DCLK/1024	-	Hz
High-pass Filter Corner Frequency -3 dB		-	0.5	-	Hz
Full-scale DC Calibration Range (Referred to Input) (Note 14)	FSCR	25	-	100	%FS
Channel-to-channel Time-shift Error (Note 15)			1.0		μs
Input/Output Characteristics					
High-level Input Voltage All Pins Except XIN and SCLK and RESET XIN SCLK and RESET Low-level Input Voltage (VD = 5 V) All Pins Except XIN and SCLK and RESET		0.6 VD+ (VD+) – 0.5 0.8 VD+		- - - 0.8	V V V
XIN SCLK and RESET		-	-	1.5 0.2 VD+	V V
Low-level Input Voltage (VD = 3.3 V) All Pins Except XIN and SCLK and RESET XIN SCLK and RESET		- - -	- -	0.48 0.3 0.2 VD+	V V V
High-level Output Voltage I _{out} = +5 mA	V _{OH}	(VD+) - 1.0	-	-	V
Low-level Output Voltage $I_{out} = -5 \text{ mA} (VD = +5V)$ $I_{out} = -2.5 \text{ mA} (VD = +3.3V)$	V _{OL}	-		0.4 0.4	V V
Input Leakage Current (Note 16	I _{in}	-	±1	±10	μA
3-state Leakage Current	I _{OZ}	-	-	±10	μA
Digital Output Pin Capacitance	C _{out}	-	5	-	pF
	Sout		U U		P'

Notes: 10. All measurements performed under static conditions.

- If a crystal is used, XIN frequency must remain between 2.5 MHz 5.0 MHz. If an external oscillator is used, XIN frequency range is 2.5 MHz - 20 MHz, but K must be set so that MCLK is between 2.5 MHz - 5.0 MHz.
- 12. If external MCLK is used, the duty cycle must be between 45% and 55% to maintain this specification.
- 13. The frequency of CPUCLK is equal to MCLK.
- 14. The minimum FSCR is limited by the maximum allowed gain register value. The maximum FSCR is limited by the full-scale signal applied to the input.
- 15. Configuration register (Config) bits PC[6:0] are set to "0000000".
- 16. The MODE pin is pulled low by an internal resistor.

CS5467

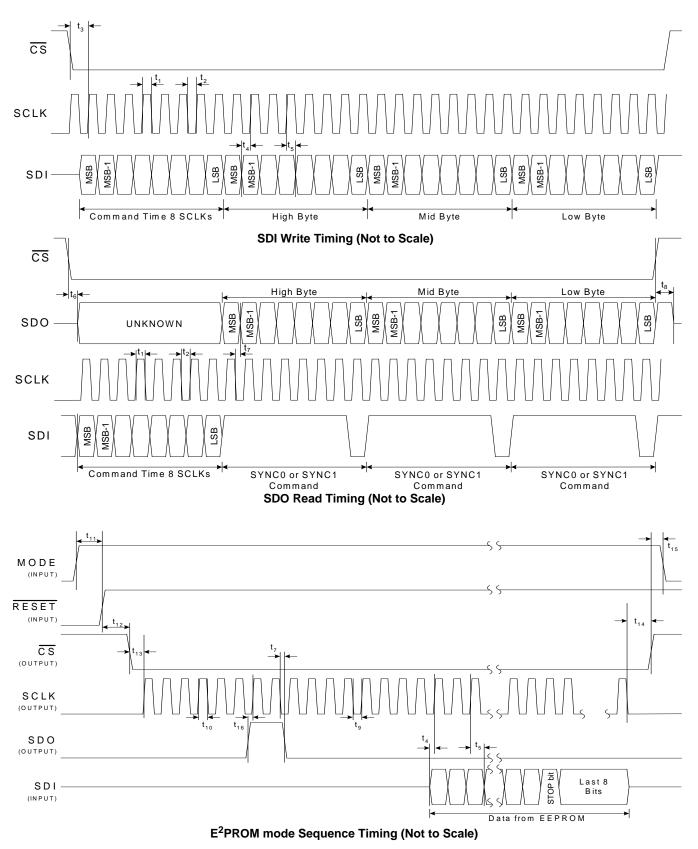
SWITCHING CHARACTERISTICS

- Min / Max characteristics and specifications are guaranteed over all Recommended Operating Conditions.
- Typical characteristics and specifications are measured at nominal supply voltages and TA = 25 °C.
- VA+ = 5 V \pm 5% VD+ = 3.3 V \pm 5% or 5 V \pm 5%; AGND = DGND = 0 V. All voltages with respect to 0 V.
- Logic Levels: Logic 0 = 0 V, Logic 1 = VD+.

Param	Symbol	Min	Тур	Max	Unit	
Rise Times (Note 17)	Any Digital Output	t _{rise}	-	- 50	1.0 -	µs ns
Fall Times (Note 17)	Any Digital Output	t _{fall}	-	- 50	1.0 -	µs ns
Start-up						_
Oscillator Start-up Time	XTAL = 4.096 MHz (Note 18)	t _{ost}	-	60	-	ms
Serial Port Timing					•	-
Serial Clock Frequency		SCLK	-	-	2	MHz
Serial Clock	t ₁ t ₂	200 200	-	-	ns ns	
SDI Timing						
CS Falling to SCLK Rising		t ₃	50	-	-	ns
Data Set-up Time Prior to SCL	K Rising	t ₄	50	-	-	ns
Data Hold Time After SCLK Ris	t ₅	100	-	-	ns	
SDO Timing						
CS Falling to SDO Driving		t ₆	-	20	50	ns
SCLK Falling to New Data Bit (I	hold time)	t ₇	-	20	50	ns
CS Rising to SDO Hi-Z		t ₈	-	20	50	ns
E ² PROM mode Timing						
Serial Clock	Pulse Width Low Pulse Width High	t ₉ t ₁₀		8 8		DCLK DCLK
MODE setup time to RESET Ri	sing	t ₁₁	50			ns
$\overline{RESET} \text{ rising to } \overline{CS} \text{ falling}$	t ₁₂	48			DCLK	
CS falling to SCLK rising	t ₁₃	100	8		DCLK	
SCLK falling to \overline{CS} rising	t ₁₄		16		DCLK	
CS rising to driving MODE low	t ₁₅	50			ns	
SDO setup time to SCLK rising	t ₁₆	100			ns	

Notes: 17. Specified using 10% and 90% points on waveform of interest. Output loaded with 50 pF.

18. Oscillator start-up time varies with crystal parameters. This specification does not apply when using an external clock source.







SWITCHING CHARACTERISTICS (Continued)

Parameter	Symbol	Min	Тур	Max	Unit
E1, E2, and E3 Timing (Note 19 and 20)				
Period	t _{period}	500	-	-	μs
Pulse Width	t _{pw}	244	-	-	μs
Rising Edge to Falling Edge	t ₃	6	-	-	μs
E2 Setup to E1 and/or E3 Falling Edge	t ₄	1.5	-	-	μs
$\overline{E1}$ Falling Edge to $\overline{E3}$ Falling Edge	t ₅	248	-	-	μs

Notes: 19. Pulse output timing is specified at DCLK = 4.096 MHz, E2MODE = 0, and E3MODE[1:0] = 0. Refer to 6.7 *Energy Pulse Outputs* on page 20 for more information on pulse output pins.

20. Timing is proportional to the frequency of DCLK.

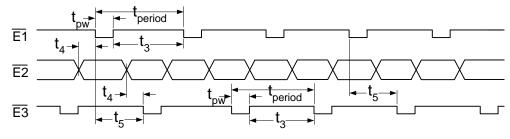


Figure 2. Timing Diagram for $\overline{E1}$, $\overline{E2}$, and $\overline{E3}$

ABSOLUTE MAXIMUM RATINGS

WARNING: Operation at or beyond these limits may result in permanent damage to the device. Normal operation is not guaranteed at these extremes.

Parameter	Symbol	Min	Тур	Max	Unit	
DC Power Supplies	(Notes 21 and 22)					
	Positive Digital	VD+	-0.3	-	+6.0	V
	Positive Analog	VA+	-0.3	-	+6.0	V
Input Current, Any Pin Except Supplies	(Notes 23, 24, 25)	I _{IN}	-	-	±10	mA
Output Current, Any Pin Except VREFOUT		I _{OUT}	-	-	100	mA
Power Dissipation	(Note 26)	Pd	-	-	500	mW
Analog Input Voltage	All Analog Pins	V _{INA}	- 0.3	-	(VA+) + 0.3	V
Digital Input Voltage	All Digital Pins	V _{IND}	-0.3	-	(VD+) + 0.3	V
Ambient Operating Temperature		Τ _Α	-40	-	85	°C
Storage Temperature		T _{stg}	-65	-	150	°C

Notes: 21. VA+ and AGND must satisfy [(VA+) - (AGND)] \leq + 6.0 V.

- 22. VD+ and AGND must satisfy [(VD+) (AGND)] \leq + 6.0 V.
- 23. Applies to all pins including continuous over-voltage conditions at the analog input pins.
- 24. Transient current of up to 100 mA will not cause SCR latch-up.
- 25. Maximum DC input current for a power supply pin is ± 50 mA.
- 26. Total power dissipation, including all input currents and output currents.





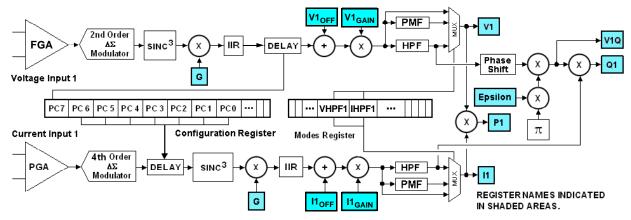


Figure 3. Signal Flow for V1, I1, P1, Q1 Measurements

4. SIGNAL PATH DESCRIPTION

The data flow for voltage and current measurement and the other calculations are shown in Figures 3, 4, and 5.

4.1 Analog-to-Digital Converters

Voltage1 channel and voltage2/temperature channel use second-order delta-sigma modulators and the two current channels use fourth-order delta-sigma modulators to convert the analog inputs to single-bit digital data streams. The converters sample at a rate of DCLK/8. This high sampling provides a wide dynamic range and simplifies anti-alias filter design.

4.2 Decimation Filters

The single-bit modulator output data is widened to 24 bits and down-sampled to DCLK/1024 with low-pass decimation filters. These decimation filters are third-order Sinc. Their outputs are passed through third-order

IIR "anti-sinc" filters, used to compensate for the amplitude roll-off of the decimation filters.

4.3 Phase Compensation

Phase compensation changes the phase of current relative to voltage by changing the sampling time in the decimation filters. The amount of phase shift is set by bits PC[7:0] in the Configuration register (*Config*) for channel 1 and bits PC[7:0] in the Control register (*Ctrl*) for channel 2.

Phase compensation, PC[7:0] is a signed two's complement binary value in the range of -1.0 to almost +1.0 output word rate (OWR) samples. For a sample rate of 4000 Hz, the delay range is ± 250 uS, a phase shift of $\pm 4.5^{\circ}$ at 50 Hz and $\pm 5.4^{\circ}$ at 60 Hz. The step size would be 0.0352° at 50 Hz and 0.0422° at 60 Hz at this sample rate.

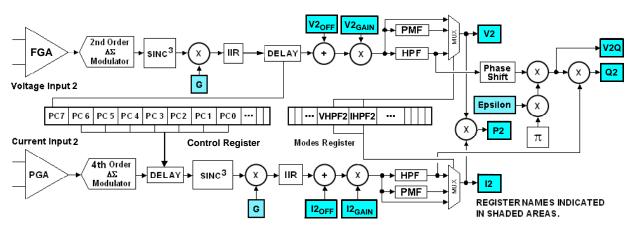


Figure 4. Signal Flow for V2, I2, P2, Q2 Measurements



4.4 DC Offset and Gain Correction

The system and chip inherently have gain and offset errors which can be removed using the gain and offset registers. (See Section 9. *System Calibration* on page 40). Each measurement channel has its own registers. For every channel, the output of the IIR filter is added to the offset register and multiplied by the gain register.

4.5 High-pass Filters

Optional high-pass filters (HPF in Figures 3 and 4) remove any DC from the selected signal paths. Subsequently, DC will also be removed from power, and all low-rate results. (see Figures 5).

Each energy channel has a current and voltage path. If an HPF is enabled in only one path, a phase-matching filter (PMF) is applied to the other path which matches the amplitude and phase delay of the HPF in the band of interest, but passes DC. For more information, see 6.5 *High-pass Filters* on page 20. The HPF filter multiplexers drive the *I*1, *V*1, *I*2, and *V*2 result registers.

4.6 Low-Rate Calculations

Low-rate results are derived from sample-rate results integrated over N samples, where N is the value stored in the Cycle Count register. The low-rate interval is the sample interval multiplied by N.

4.7 RMS Results

The root mean square (*RMS* in Figure 5) calculations are performed on N instantaneous voltage and current samples, using the formula:

$$I_{RMS} = \sqrt{\frac{\sum_{n=0}^{N-1} I_n^2}{N}}$$



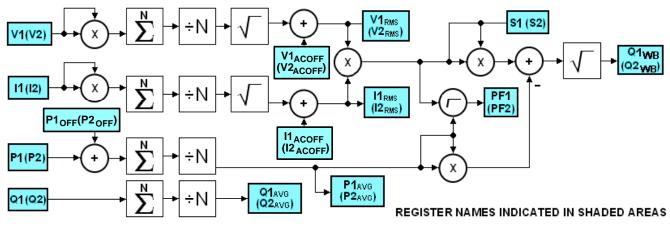


Figure 5. Low-rate Calculations

4.8 Power and Energy Results

The instantaneous voltage and current samples are multiplied to obtain the instantaneous power (*P1*, *P2*) (see Figure 3 and 4). The product is then averaged over *N* conversions to compute active power (*P1*_{AVG}, $P2_{AVG}$).

Apparent power (S1, S2) is the product of RMS voltage and current as shown:

$$S = V_{RMS} \times I_{RMS}$$

Power factor (*PF1*, *PF2*) is active power divided by apparent power as shown below. The sign of the power factor is determined by the active power.

$$\mathsf{PF} = \frac{\mathsf{P}_{\mathsf{Active}}}{\mathsf{S}}$$

Wideband reactive power ($Q1_{WB}$, $Q2_{WB}$) is calculated by doing a vector subtraction of active power from apparent power. $Q_{WB} = \sqrt{S^2 - P_{Active}^2}$

Quadrature power (Q1, Q2) are sample rate results obtained by multiplying instantaneous current (I1, I2) by instantaneous quadrature voltage (V1Q, V2Q) which are created by phase shifting instantaneous voltage (V1, V2) 90 degrees using first-order integrators. (See Figure 3 and 4). The gain of these integrators is inversely related to line frequency, so their gain is corrected by the *Epsilon* register, which is based on line frequency.

Reactive power ($Q1_{Avg}$, $Q2_{AvG}$) is generated by integrating the instantaneous quadrature power over *N* samples.

Active power ($P1_{AVG}$, $P2_{AVG}$), apparent power (S1, S2), and reactive power ($Q1_{AVG}$, $Q2_{AVG}$) of the two channels are summed up and then divided by 2. The calculation results are placed in E_{PULSE} , S_{PULSE} , and Q_{PULSE} registers which can be configured to drive energy pulse outputs. (See Figure 6.)

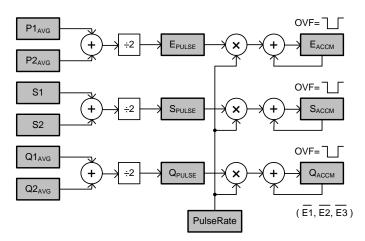


Figure 6. Two-channel Power Summation



4.9 Peak Voltage and Current

Peak current ($I1_{PEAK}$, $I2_{PEAK}$) and peak voltage ($V1_{PEAK}$, $V2_{PEAK}$) are the largest current and voltage samples detected in the previous low-rate interval.

4.10 Power Offset

The power offset registers, $P1_{OFF}$ ($P2_{OFF}$) can be used to offset erroneous power sources resident in the system not originating from the power line. Residual power offsets are usually caused by crosstalk into current paths from voltage paths or from ripple on the meter or chip's power supply, or from inductance from a nearby transformer.

These offsets can be either positive or negative, indicating crosstalk coupling either in phase or out of phase with the applied voltage input. The power offset registers can compensate for either condition.

To use this feature, measure the average power at no load using either Single or Continuous Conversion commands. Take the measured result (from the $P1_{AVG}$ ($P2_{AVG}$) register), invert (negate) the value and write it to the associated power offset register, $P1_{OFF}$ ($P2_{OFF}$).



5. PIN DESCRIPTIONS

5.1 Analog Pins

The CS5467 has four differential inputs: VIN1 \pm , VIN2 \pm , IIN1 \pm , and IIN2 \pm are the voltage1, voltage2, current1, and current2 inputs, respectively. A single-ended power fail monitor input, voltage reference input, and voltage reference output are also available.

5.1.1 Voltage1 & Voltage2 Inputs

The output of the line voltage resistive divider or transformer is connected to the VIN1+ (VIN2+) and VIN1- (VIN2-) input pins of the CS5467. The voltage channel is equipped with a 10x, fixed-gain amplifier. The full-scale signal level that can be applied to the voltage channel is ±250 mV. If the input signal is a sine wave, the maximum RMS voltage is 250 mVp / $\sqrt{2} \approx$ 176.78 mVRMS which is approximately 70.7% of maximum peak voltage.

5.1.2 Current1 & Current2 Inputs

The output of the current-sensing resistor or transformer is connected to the IIN1+ (IIN2+) and IIN1- (IIN2-) input pins of the CS5467. To accommodate different current-sensing elements, the current channel incorporates a programmable gain amplifier (PGA) with two selectable input gains. The full-scale signal level for the current channels is ± 50 mV or ± 250 mV. If the input signal is a sine wave, the maximum RMS voltage is 35.35 mVRMS or 176.78 mVRMS which is approximately 70.7% of maximum peak voltage.

5.1.3 Power Fail Monitor Input

An analog input (PFMON) is provided to determine when a power loss is imminent. By connecting a resistive divider from the unregulated meter power supply to the PFMON input, an interrupt can be generated, or the Low Supply Detected (LSD) *Status* register bit can be monitored to indicate low-supply conditions. The PF-MON input has a comparator that trips around the level of the voltage reference input (VREFIN).

5.1.4 Voltage Reference Input

The CS5467 requires a stable voltage reference of 2.5 V applied to the VREFIN pin. This reference can be supplied from an external voltage reference or from the VREFOUT output. A bypass capacitor of at least 0.1 μ F is recommended at the VREFIN pin.

5.1.5 Voltage Reference Output

The CS5467 generates a 2.5 V reference (VREFOUT). It is suitable for driving the VREFIN pin, but has very little fan-out capacity and is not recommended for driving external circuits.

5.1.6 Crystal Oscillator

An external quartz crystal can be connected to the XIN and XOUT pins as shown in Figure 7. To reduce system cost, each pin is supplied with an on-chip, phase-shifting capacitor to ground.

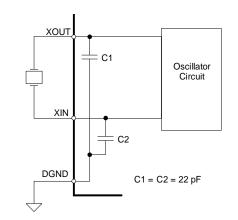


Figure 7. Oscillator Connections

Alternatively, an external clock source can be connected to the XIN pin.

5.2 Digital Pins

5.2.1 Reset Input

The active-low RESET pin, when asserted, will halt all CS5467 operations and reset internal hardware registers and states. When de-asserted, an initialization sequence begins, setting default register values.

5.2.2 CPU Clock Output

A logic-level clock output (CPUCLK) is provided at the crystal frequency to drive an external CPU or microcontroller clock. Two phase choices are available.

5.2.3 Interrupt Output

The INT pin indicates an enabled Internal Status register (*Status*) bit is set. *Status* register bits indicate conditions such as data ready, modulator oscillations, low supply, voltage sag, current faults, numerical overflows, and result updates.

5.2.4 Energy Pulse Outputs

The CS5467 provides three pins ($\overline{E1}$, $\overline{E2}$, $\overline{E3}$) for pulse energy outputs. These pins can also be used to output other conditions, such as voltage1 sign, power fail monitor, or energy sign.



5.2.5 Serial Interface

The CS5467 provides 5 pins, SCLK, SDI, SDO, \overline{CS} , and MODE for communication between a host microcontroller or serial E²PROM and the CS5467.

MODE is an input that, when high, indicates to the CS5467 that a serial E^2 PROM is being used instead of a host microcontroller. It has a weak pull-down allowing it to be left unconnected if microcontroller mode is used.

SCLK is used to shift and qualify serial data. Serial data changes as a result of the falling edge of SCLK and is valid during the rising edge. It is a Schmitt-trigger input

for host microcontrollers, and a driven output for serial E^2 PROMs.

SDI is the serial data input to the CS5467.

SDO is the serial data output from the CS5467. It's output drivers are disabled whenever \overline{CS} is de-asserted, allowing other devices to drive the SDO line.

 $\overline{\text{CS}}$ is the chip select input for the serial bus. A high logic level de-asserts it, tri-stating the SDO pin and clearing the serial interface. A low logic level enables the serial port. This pin may be tied low for systems not requiring multiple SDO drivers. $\overline{\text{CS}}$ is a driven output when interfacing to serial E²PROMs.



6. SETTING UP THE CS5467

6.1 Clock Divider

The internal clock to the CS5467 needs to operate around 4 MHz. However, by using the internal clock divider, a higher crystal frequency can be used. This is important when driving an external microcontroller requiring a faster clock and using the CPUCLK output.

K is the divide ratio from the crystal input to the internal clock and is selected with Configuration register (*Config*) bits K[3:0]. It has a range of 1 to 16. A value of zero results in a setting of 16.

6.2 CPU Clock Inversion

By default, CPUCLK is inverted from XIN. Setting Configuration register bit iCPU removes this inversion. This can be useful when one phase adds more noise to the system than the other.

6.3 Interrupt Pin Behavior

The behavior of the INT pin is controlled by the IMODE and IINV bits in the Configuration register as shown.

IMODE	IINV	INT Pin	
0	0	Active-low Level	
0	1	Active-high Level	
1	0	Low Pulse	
1	1	High Pulse	

Table 1. Interrupt Configuration

If IMODE = 1, the duration of the \overline{INT} pulse will be two DCLK cycles, where DCLK = MCLK/K.

6.4 Current Input Gain Ranges

Control register bits I1gain (I2gain) select the input range of the current inputs.

l1gain, l2gain	Maximum Input	Gain
0	±250 mV	10x
1	±50 mV	50x

 Table 2. Current Input Gain Ranges

6.5 High-pass Filters

Mode Control (*Modes*) register bits VHPF and IHPF activate the HPF in the voltage and current paths, respectively. Each energy channel has separate VHPF and IHPF bits. When a high-pass filter is enabled in only one path within a channel, a phase matching filter (PMF) is applied to the other path within that channel. The PMF filter matches the amplitude and phase response of the HPF in the band of interest, but passes DC.

VHPF	IHPF	Filter Configuration
0	0	No filter on Voltage or Current
0	1	HPF on Current, PMF on Voltage
1	0	HPF on Voltage, PMF on Current
1	1	HPF on Current and Voltage

Table 3.	High-pass	Filter	Configuration
----------	-----------	--------	---------------

6.6 Cycle Count

Low-rate calculations, such as average power and RMS voltage and current integrate over several (*N*) output word rate (OWR) samples. The duration of this averaging window is set by the Cycle Count (*N*) register. By default, Cycle Count is set to 4000 (1 second at output word rate [OWR] of 4000 Hz). The minimum value for Cycle Count is 10.

6.7 Energy Pulse Outputs

By default, $\overline{E1}$ outputs total active energy, $\overline{E3}$, total reactive energy, and $\overline{E2}$, the sign of both active and reactive energy. (See Figure 2. *Timing Diagram for E1, E2, and E3* on page 13.)

Three pairs of bits in the Mode Control (*Modes*) register control the operation of these outputs. These bits are named E1MODE[1:0], E2MODE[1:0], and E3MODE[1:0]. Some combinations of these bits override others, so read the following paragraphs carefully.

The $\overline{E2}$ pin can output energy sign, <u>or total</u> apparent energy. Table 4 lists the functions of $\overline{E2}$ as controlled by E2MODE[1:0] in the *Modes* register.

E2MODE1	E2MODE0	E2 output		
0	0	Energy Sign		
0	1	Total Apparent Energy		
1	0	Not Used		
1	1	Enable E1MODE		

Note: E2MODE[1:0]=3 is a special mode.

Table 4. E2 Pin Configuration

The $\overline{E3}$ pin can output total reactive energy, power fail monitor status, voltage1 sign, or total apparent energy. Table 5 lists the functions of $\overline{E3}$ as controlled by E3MODE[1:0] in the *Modes* register when E1MODE is not enabled.

E3MODE1	E3MODE0	E3 output
0	0	Total Reactive Energy
0	1	Power Fail Monitor
1	0	Voltage1 Sign
1	1	Total Apparent Energy

Table 5. $\overline{E3}$ Pin Configuration

When both E2MODE bits are high, the E1MODE bits are enabled, allowing active, apparent, reactive, or wide band reactive energy for **both** energy channels to be output on E1 and E2. Table 6 lists the functions of E1 and E2 with E1MODE enabled.

E1MODE1	E1MODE0	E1 / E2 outputs
0	0	Active Energy
0	1	Apparent Energy
1	0	Reactive Energy
1	1	Wideband Reactive

Table 6. E1 / E2 Modes

When E1MODE bits are enabled, the $\overline{E3}$ pin outputs <u>either the</u> power fail monitor status, or the sign of the $\overline{E1}$ and $\overline{E2}$ outputs. Table 7 list the functions of the $\overline{E3}$ pin using E3MODE[1:0] in the *Modes* register when E1MODE is enabled.

E3MODE1	E3MODE0	E3 output
0	0	Power Fail Monitor
0	1	Energy Sign
1	0	not used
1	1	not used

Table 7.	E3 Pin	with	E1MODE	enabled
			LIMODE	onabioa

6.8 No Load Threshold

The No Load Threshold register ($Load_{MIN}$) is used to zero out the contents of E_{PULSE} and Q_{PULSE} registers if their magnitude is less than the $Load_{MIN}$ register value.

6.9 Energy Pulse Width

<u>Note:</u> Energy Pulse Width (*PulseWidth*) only applies to E1, E2, or E3 pins that are configured to output pulses. When any are configured to output steady-state signals, such as voltage1 sign, power fail monitor, or energy sign, pulse widths and output rates do not apply.

The pulse width time (t_{pw}) in Figure 2, is set by the value in the *PulseWidth* register which is an integer multiple of the sample or output word rate (OWR). At OWR of 4000 Hz (a period of 250 uS) $t_{pw} = PulseWidth \times$ 250 uS. By default, *PulseWidth* is set to 1.

6.10 Energy Pulse Rate

The full-scale pulse frequency of enabled $\overline{E1}$, $\overline{E2}$, $\overline{E3}$ pins is the value in *PulseRate* x output word rate (OWR)/2. The actual pulse frequency is the full-scale pulse frequency multiplied by the pulse register's (*E_{PULSE}*, *S_{PULSE}*, or *Q_{PULSE}*) value.

Example:

If the output word rate (OWR) is 4000 Hz, and the *PulseRate* register is set to 0.05, the full-rate pulse frequency is 0.05 x 4000 / 2 = 100 Hz. If the E_{PULSE} register, driving E1, is 0.4567, the pulse output rate on E1 will be 100 Hz x 0.4567 = 45.67 Hz.

6.11 Voltage Sag/Current Fault Detection

Voltage sag detection is used to determine when averaged voltage falls below a predetermined level for a specified interval of time. Current fault detection determines when averaged current falls below a predetermined level for a specified interval of time.

The specified interval of time (duration) is set by the value in the $V1Sag_{DUR}$ ($V2Sag_{DUR}$) and $I1Fault_{DUR}$ ($I2Fault_{DUR}$) registers. Setting any of these to zero (default) disables the detect feature for the given channel. The value is in output word rate (OWR) samples. The predetermined level is set by the values in the $V1Sag_{LEVEL}$ ($V2Sag_{LEVEL}$) and $I1Fault_{LEVEL}$ ($I2Fault_{LEVEL}$) registers.



For each enabled input channel, the measured value is rectified and compared to the associated level register. Over the duration window, the number of samples above and below the level are counted. If the number of samples below the level exceeds the number of samples above, a *Status* register bit $V1_{SAG}$ ($V2_{SAG}$), $I1_{FAULT}$ ($I2_{FAULT}$) is set, indicating a sag or fault condition. (see Figure 8)..

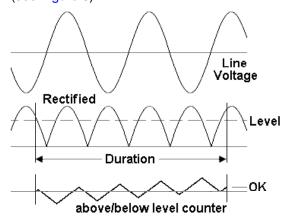


Figure 8. Sag and Fault Detect

6.12 Epsilon

The *Epsilon* register is used to set the gain of the 90° phase shift used in the quadrature power calculation.

The value in the *Epsilon* register is the ratio of the line frequency to the output word rate (OWR). It is, by default, 50/4000 (0.0125), for 50 Hz line and 4000 Hz sample (OWR) frequencies.

For 60 Hz line frequency, it is 60/4000 (0.015). Other output word rates (OWR) can be used.

Epsilon can also be calculated automatically by the CS5467 by setting the AFC bit in the Mode Control (*Modes*) register. The Frequency Update bit (FUP) in the *Status* register is set every time the *Epsilon* register has been automatically updated.

6.13 Temperature Measurement

The on-chip temperature sensor is designed to measure temperature and optionally compensate for temperature drift of the voltage reference. It uses the VBE of a transistor to determine temperature.

In the CS5467, voltage2 and temperature are multiplexed on one ADC channel. To initiate a temperature measurement, write *1* to the Temperature Measurement (T_{MEAS}) register. T_{MEAS} will go through counts 1, 2, 4, and back to 0. Wait for T_{MEAS} to return to 0. When done, Temperature (*T*) is updated. The *Status* register bit TUP also indicates when the Temperature register is

updated. The Voltage2 register (V2) will not update during the temperature measurement, but resume measurement afterwards.

Temperature measurements are stored in the Temperature register (7) which, by default, is configured to a range of ± 128 degrees on the Celsius (°C) scale.

The application program can change both the scale and range of Temperature (*T*) by changing the Temperature Gain (T_{GAIN}) and Temperature Offset (T_{OFF}) registers.

Two values must be known — the transistor's Δ VBE per degree, and the transistor's VBE at 0 degrees. At the time of this publication, these values are:

 ΔVBE (per degree) = 0.2769523 mV/°C or °K

V_{BE}0 = 79.2604368 mV at 0°C

To determine the values to write to T_{GAIN} and T_{OFF} , use the following formulae:

$$T_{GAIN} = AD_{FS} / \Delta VBE / T_{FS} \times 2^{17}$$
$$T_{OFF} = -V_{BE}0 / AD_{FS} \times 2^{23}$$

In the above equations, AD_{FS} is the full-scale input range of the temperature A/D converter or 833.333 mV and T_{FS} is the desired full-scale range of the Temperature (*T*) register. The binary exponents are the bit positions of the binary point of these registers.

To use the Celsius scale (°C) and cover the chip's operating temperature range of -40°C to +85°C, the Temperature register range needs to be \pm 128 degrees. T_{FS} should be 128 degrees.

 $T_{GAIN} = 833.333 / 0.2769523 / 128 \times 131072$

= 3081155 (0x2F03C3)

 $T_{OFF} = -79.2604368 / 833.333 \times 8388608$ = -797862 (0xF3D35A)

These are the actual default values for these registers.

 T_{GAIN} and T_{OFF} can also be used to calibrate the gain and/or offset of the temperature sensor or A/D converter. (See Section 9. *System Calibration* on page 40).

To use the Kelvin (°K) scale, simply add 273 times Δ VBE / AD_{FS} x 2²³ to T_{OFF} since 0°C = 273°K,. You will also need more range. Since -40°C to +85°C is 233°K to 358°K, a T_{FS} of 512 degrees should be used in the T_{GAIN} calculation.

To use the Fahrenheit (°F) scale, multiply Δ VBE by 5/9 and add 32 times the new Δ VBE / AD_{FS} x 2²³ to T_{OFF} since 0°C = 32°F. You will also want to use a T_{FS} of 256 degrees to cover the -40°C to +85°C range.



7. USING THE CS5467

7.1 Initialization

The CS5467 uses a power-on-reset circuit (POR) to provide an internal reset until the analog voltage reaches 4.0 V. The RESET input pin can also be used by the application circuit to reset the part.

After RESET is removed and the oscillator is stable, an initialization program is executed to set the default register values.

A Software Reset command is also provided to allow the application to run the initialization program without removing power or asserting RESET.

The application should avoid sending commands during initialization. The DRDY bit in the *Status* register indicates when the initialization program has completed.

7.2 Power-down States

The CS5467 has two power-down states, stand-by and sleep. In the stand-by state, all circuitry except the voltage reference and crystal oscillator is powered off. In sleep state, all circuitry except the instruction decoder is powered off.

To return the device to the active state, send a Wakeup/Halt command to the device. When returning from stand-by mode, registers will retain their contents prior to entering the stand-by state. When returning from sleep mode, a complete initialization occurs.

7.3 Voltage Tamper Correction

The CSS5467 provides compensation for meter tampering on voltage channels.

If the application detects that the voltage input has been impaired it may choose to use the fixed internal RMS voltage reference by setting the VFIX bit in the *Modes* register. The value of this reference (VF_{RMS}) is by default 0.707107 (full-scale RMS) but can be changed by the application program. (See figure 9)

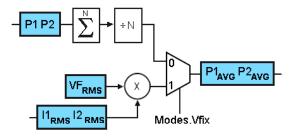


Figure 9. Fixed RMS Voltage Selection



7.4 Command Interface

Commands and data are transferred most-significant bit (MSB) first. Figure 1 on page 12, defines the serial port timing. Commands are clocked in on SDI using SCLK. They are a single byte (8 bits) long and fall into one of four basic types:

- 1. Register Read
- 2. Register Write
- 3. Synchronizing
- 4. Instructions

Register reads will cause up to four bytes of register data to be clocked out, MSB first on the SDO pin by SCLK. During this time, other commands can be clocked in on the SDI pin. Other commands will not interrupt read data, except another register read, which will cause the new read data to appear on SDO.

Synchronizing can be sent while read data is being clocked out if no other commands need to be sent.

Synchronizing commands are also used to synchronize the serial port to a byte boundary. The CS and RESET pins will also synchronize the serial port.

Register writes require three bytes of write data to follow, clocked in on the SDI pin, MSB first by SCLK.

Instructions are commands that will interrupt any instruction currently executing and begin the new instruction. These include conversions, calibrations, power control, and soft reset.

(See Section 7.6 Commands on page 25).

7.5 Register Paging

Read and Write commands access one of 32 registers within a specified page. The Register Page Select register's (*Page*) default value is 0. To access registers in another page, write the desired page number to the *Page* register. The *Page* register is always at address 31 and is accessible from within any page.



7.6 Commands

All commands are 1 byte (8 bits) long. Many command values are unused and should NOT be written by the application program. All commands except register reads, register writes, or synchronizing commands will abort any conversion, calibration, or any initialization sequence currently executing. This includes reset. No commands other than reads or synchronizing should be executed until the reset sequence completes.

7.6.1 Conversion

B7	B6	B5	B4	B3	B2	B1	B0
1	1	1	0	CC	0	0	0

Executes a conversion (measurement) program.

CC

Continuous/Single Conversion 0 = Perform a Single Conversion (0xE0) 1 = Perform Continuous Conversion (0xE8)

7.6.2 Synchronization (SYNC0 and SYNC1)

B7	B6	B5	B4	B3	B2	B1	B0
1	1	1	1	1	1	1	SYNC

The serial interface is bidirectional. While reading data on the SDO output, the SDI input must be receiving commands. If no command is needed during a read, SYNC0 or SYNC1 commands can be sent while read data is received on SDO.

The serial port is normally initialized by de-asserting \overline{CS} . An alternative method of initialization is to send 3 or more SYNC1 commands followed by a SYNC0. This is useful in systems where \overline{CS} is not used and tied low.

7.6.3 Power Control (Stand-by, Sleep, Wake-up/Halt and Software Reset)

B7	B6	B5	B4	B3	B2	B1	B0
1	0	S1	S0	0	0	0	0

The CS5467 has two power-down states, stand-by and sleep. In stand-by, all circuitry except the voltage reference and clocks are turned off. In sleep mode, all circuitry except the command decoder is turned off. A Wake-up/Halt command restores full-power operation after stand-by and issues a hardware reset after sleep. The Software Reset command is a program that emulates a pin reset and is not a power control function.

S[1:0] 00 = Software Reset 01 = Sleep 10 = Wake-up/Halt 11 = Stand-by



7.6.4 Calibration

B7		B5					B0
1	0	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0

The CS5467 can perform gain and offset calibrations using either DC or AC signals. Proper input levels must be applied to the current inputs and voltage input before performing calibrations.

CAL[5:4]*	00 = DC Offset 01 = DC Gain 10 = AC Offset 11 = AC Gain
CAL[3:0]	0001 = Current for Channel 1 0010 = Voltage for Channel 1 0100 = Current for Channel 2 1000 = Voltage for Channel 2
Note:	Anywhere from 1 to all 4 channels can be calibrated simultaneously.

7.6.5 Register Read and Write

B7	B6	B5	B4	B3	B2	B1	B0
0	W/R	RA4	RA3	RA2	RA1	RA0	0

Read and Write commands provide access to on-chip registers. After a Read command, the addressed data can be clocked out the SDO pin by SCLK. After a Write command, 24 bits of write data must follow. The data is transferred to the addressed register after the 24th data bit is received. Registers are organized into pages of 32 addresses each. To access a desired page, write its number to the *Page* register at address 31.

W/R

Write/Read control

0 = Read

1 = Write

RA[4:0] Register address.

Page 0 Registers

Address 0 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18	RA[4:0] 00000 00001 00010 00011 00100 00101 00110 00111 01000 01001 01011 01100 01101 01101 01111 01110 01111 10000 10001	$\frac{\text{Name}}{\text{Config}}$ 11 $V1$ $P1$ $P1_{AVG}$ 11_{RMS} $V1_{RMS}$ 12 $V2$ $P2$ $P2_{AVG}$ 12_{RMS} $V2_{RMS}$ $Q1_{AVG}$ $Q1$ $Status$ $Q2_{AVG}$ $Q2$ 11	Description Configuration Instantaneous Current Channel 1 Instantaneous Voltage Channel 1 Instantaneous Power Channel 1 Active Power Channel 1 RMS Current Channel 1 RMS Voltage Channel 1 Instantaneous Current Channel 2 Instantaneous Voltage Channel 2 Instantaneous Voltage Channel 2 Active Power Channel 2 RMS Current Channel 2 RMS Voltage Channel 2 RMS Voltage Channel 2 RMS Voltage Channel 1 Instantaneous Quadrature Power Channel 1 Internal Status Reactive Power Channel 2 Instantaneous Quadrature Power Channel 2 Reactive Power Channel 2
			Instantaneous Quadrature Power Channel 2
18	10010	I1 _{PEAK}	Peak Current Channel 1
19	10011	V1 _{PEAK}	Peak Voltage Channel 1
20	10100	S1	Apparent Power Channel 1
21	10101	PF1	Power Factor Channel 1
22	10110	12 _{PEAK}	Peak Current Channel 2
23	10111	V2 _{PEAK}	Peak Voltage Channel 2
24 25	11000 11001	S2 PF2	Apparent Power Channel 2 Power Factor Channel 2
26	11010	Mask	Interrupt Mask
27	11010	T	Temperature
28	11100	Ctrl	Control
29	11101	E _{PULSE}	Active Energy Pulse Output
30	11110	SPULSE	Apparent Energy Pulse Output
31 R	11111	Q _{PULSE}	Reactive Energy Pulse Output
31 W	11111	Page	Register Page Select

Warning: *Do not* write to unpublished register locations.



Page1 Registers

Address	<u>RA[4:0]</u>	<u>Name</u>	Description
0	00000	I1 _{OFF}	Current DC Offset Channel 1
1	00001	I1 _{GAIN}	Current Gain Channel 1
2	00010	V1 _{OFF}	Voltage DC Offset Channel 1
3	00011	V1 _{GAIN}	Voltage Gain Channel 1
4	00100	P1 _{OFF}	Power Offset Channel 1
5	00101	I1 _{ACOFF}	Current AC (RMS) Offset Channel 1
6	00110	V1 _{ACOFF}	Voltage AC (RMS) Offset Channel 1
7	00111	I2 _{OFF}	Current DC Offset Channel 2
8	01000	I2 _{GAIN}	Current Gain Channel 2
9	01001	V2 _{OFF}	Voltage DC Offset Channel 2
10	01010	V2 _{GAIN}	Voltage Gain Channel 2
11	01011	P2 _{OFF}	Power Offset Channel 2
12	01100	12 _{ACOFF}	Current AC (RMS) Offset Channel 2
13	01101	V2 _{ACOFF}	Voltage AC (RMS) Offset Channel 2
14	01110	PulseWidth	Pulse Output Width
15	01111	PulseRate	Pulse Output Rate (frequency)
16	10000	Modes	Mode Control
17	10001	Epsilon	Ratio of Line to Sample Frequency
19	10011	Ν	Cycle Count (Number of OWR Samples in One Low-rate Interval)
20	10100	Q1 _{WB}	Wideband Reactive Power from Power Triangle Channel 1
21	10101	Q2 _{WB}	Wideband Reactive Power from Power Triangle Channel 2
22	10110	T _{GAIN}	Temperature Sensor Gain
23	10111	T _{OFF}	Temperature Sensor Offset
25	11001	T _{SETTLE}	Filter Settling Time for Conversion Startup
26	11010	Load _{MIN}	No Load Threshold
27	11011	VF _{RMS}	Voltage RMS Fixed Reference
28	11100	G	System Gain
29	11101	Time	System Time (in samples)
31 W	11111	Page	Register Page Select

Page2 Registers

<u>Address</u>	<u>RA[4:0]</u>	<u>Name</u>	Description
0	00000	V1Sag _{DUR}	V Sag Duration Channel 1
1	00001	V1Sag _{LEVEL}	V Sag Level Channel 1
4	00100	I1Fault _{DUR}	I Fault Duration Channel 1
5	00101	I1Fault _{LEVEL}	I Fault Level Channel 1
8	01000	V2Sag _{DUR}	V Sag Duration Channel 2
9	01001	V2Sag _{LEVEL}	V Sag Level Channel 2
12	01100	I2Fault _{DUR}	I Fault Duration Channel 2
13	01101	I2Fault _{LEVEL}	I Fault Level Channel 2
31 W	11111	Page	Register Page Select

Page5 Register

<u>Address</u>	<u>RA[4:0]</u>	<u>Name</u>	Description
26	11010	T _{MEAS}	Temperature Measurement
31 W	11111	Page	Register Page Select

Warning: *Do not* write to unpublished register locations.

8. REGISTER DESCRIPTIONS

- 1. "Default" = bit states after power-on or reset
- 2. DO NOT write a "1" to any unpublished register bit.
- 3. DO NOT write to any unpublished register address.

8.1 Page Register

8.1.1 Page – Address: 31, Write-only, can be written from ANY page.

MSB						LSB
2 ⁶	2 ⁵	2 ⁴	2 ³	2 ²	2 ¹	2 ⁰

Default = 0

Register Read and Write commands contain only 5 address bits. But the internal address bus of the CS5467 is 12 bits wide. Therefore, registers are organized into "Pages". There are 128 pages of 32 registers each. The *Page* register provides the 7 high-order address bits and selects one of the 128 register pages. Not all pages are used,

Page is a write-only integer containing 7 bits.

8.2 Page 0 Registers

8.2.1 Configuration (Config) – Address: 0

23	22	21	20	19	18	17	16
PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0
15	14	13	12	11	10	9	8
EWA	-	-	IMODE	IINV	-	-	-
7	6	5	4	3	2	1	0
-	-	-	iCPU	K3	K2	K1	K0

Default = 1 (K=1)

PC[7:0]	Phase compensation for channel 1. Sets a delay in voltage, relative to current. Phase is signed and in the range of $-1.0 \le$ value < 1.0 sample (OWR) intervals.
EWA	Allows the $\overline{E1}$ and $\overline{E2}$ pins to be configured as open-drain outputs. 0 = Normal Outputs 1 = Open-drain Outputs
IMODE, IINV	Interrupt configuration. Selects INT pin behavior. 00 = Low Logic Level When Asserted 01 = High Logic Level When Asserted 10 = Low-going Pulse on New Interrupt 11 = High-going Pulse on New Interrupt
iCPU	Inverts the CPUCLK output. 0 = Default 1 = Invert CPUCLK.
K[3:0]	Clock divider. Divides MCLK by K to generate internal clock DCLK. (DCLK = MCLK/K). K is unsigned and in the range of 1 to 16. When zero, $K = 16$. At reset, $K = 1$.



8.2.2 Instantaneous Current (I1, I2), Voltage (V1, V2), and Power (P1, P2) Address: 1 (I1), 2 (V1), 3 (P2), 7 (I2), 8 (V2), 9 (P2)

MSB								 _						LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	 2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

I1 (*I2*) and *V1* (*V2*) contain instantaneous current and voltage, respectively, which are multiplied to yield instantaneous power, *P1* (*P2*). These are two's complement values in the range of $-1.0 \le$ value < 1.0, with the binary point to the right of the MSB.

8.2.3 Active Power ($P1_{AVG}$, $P2_{AVG}$) Address: 4 ($P1_{AVG}$), 10 ($P2_{AVG}$)

MSB														LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	 2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

Instantaneous power is averaged over each low-rate interval (*N* samples) to compute active power, $P1_{AVG}$ ($P2_{AVG}$). These are two's complement values in the range of -1.0 \leq value < 1.0, with the binary point to the right of the MSB.

^{8.2.4} RMS Current ($I1_{RMS}$, $I2_{RMS}$) and Voltage ($V1_{RMS}$, $V2_{RMS}$) Address: 5 ($I1_{RMS}$), 6 ($V1_{RMS}$), 11 ($I2_{RMS}$), 12 ($V2_{RMS}$)

MSB								 						LSB
2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	2 ⁻⁸	 2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³	2 ⁻²⁴

 $I1_{RMS}$ ($I2_{RMS}$) and $V1_{RMS}$ ($V2_{RMS}$) contain the root mean square (RMS) values of I1 (I2) and V1 (V2), calculated each low-rate interval. These are unsigned values in the range of $0 \le$ value < 1.0, with the binary point to the left of the MSB.

^{8.2.5} Instantaneous Quadrature Power (Q1, Q2) Address: 14 (Q1), 17 (Q2)

MSB														LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	 2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

Instantaneous quadrature power, Q1(Q2), the product of voltage1 (voltage2) shifted 90 degrees and current1 (current2). These are two's complement values in the range of $-1.0 \le$ value < 1.0, with the binary point to the right of the MSB.

8.2.6 Reactive Power ($Q1_{Avg}$, $Q2_{AVG}$) Address: 13 ($Q1_{AVG}$), 16 ($Q2_{AVG}$)

MSB														LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	 2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

Reactive power $Q1_{AVG}$ ($Q2_{AVG}$) is Q1 (Q2) averaged over every N samples. These are two's complement values in the range of -1.0 \leq value < 1.0, with the binary point to the right of the MSB.



8.2.7 Peak Current (I1_{PEAK}, I2_{PEAK}) and Peak Voltage (V1_{PEAK}, V2_{PEAK})

Address: 18 (*I1_{PEAK}*), 19 (*V1_{PEAK}*), 22 (*I2_{PEAK}*), 23 (*V2_{PEAK}*)

MSB														LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	 2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

Peak current, $I1_{PEAK}$ ($I2_{PEAK}$) and peak voltage, $V1_{PEAK}$ ($V2_{PEAK}$) are the instantaneous current and voltage samples with the greatest magnitude detected during the last low-rate interval. These are two's complement values in the range of -1.0 \leq value < 1.0, with the binary point to the right of the MSB.

8.2.8 Apparent Power (S1, S2)

Address: 20 (S1), 24 (S2)

MSB														LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	 2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

Apparent power S1 (S2) is the product of $V1_{RMS}$ and $I1_{RMS}$ ($V2_{RMS}$ and $I2_{RMS}$), These are two's complement values in the range of 0 \leq value < 1.0, with the binary point to the right of the MSB.

8.2.9 Power Factor (PF1, PF2)

Address: 21 (PF1), 25 (PF2)

	MSB													LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	 2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

Power factor is calculated by dividing active power by apparent power. The sign is determined by the active power sign. These are two's complement values in the range of $-1.0 \le$ value < 1.0, with the binary point to the right of the MSB.

8.2.10 Temperature (T) – Address: 27

MSB														LSB
-(2 ⁷)	2 ⁶	2 ⁵	2 ⁴	2 ³	2 ²	2 ¹	2 ⁰	 2 ⁻¹⁰	2 ⁻¹¹	2 ⁻¹²	2 ⁻¹³	2 ⁻¹⁴	2 ⁻¹⁵	2 ⁻¹⁶

T contains results from the on-chip temperature measurement. By default, *T* uses the Celsius scale, and is a two's complement value in the range of $-128.0 \le value < 128.0$ (°C), with the binary point to the right of bit 16.

T can be rescaled by the application using the T_{GAIN} and T_{OFF} registers.

8.2.11 Active, Apparent, and Reactive Energy Pulse Outputs (E_{PULSE}, S_{PULSE}, Q_{PULSE}) Address: 29 (E_{PULSE}), 30 (S_{PULSE}), 31 (Q_{PULSE})

MSB														LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	 2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

These drive the pulse outputs when configured to do so. These are two's complement values in the range of $-1.0 \le$ value < 1.0, with the binary point to the right of the MSB. Refer to 4.8 *Power and Energy Results* on page 16.



8.2.12 Internal Status (Status) and Interrupt Mask (Mask) Address: 15 (Status); 26 (Mask)

23	22	21	20	19	18	17	16
DRDY	I2OR	V2OR	CRDY	I2ROR	V2ROR	I10R	V1OR
15	14	13	12	11	10	9	8
E2OR	I1ROR	V1ROR	E1OR	I1FAULT	V1SAG	I2FAULT	V2SAG
7	6	5	4	3	2	1	0
TUP	V2OD	I2OD	V10D	I10D	LSD	FUP	IC

Default = 1 (*Status*), 0 (*Mask*)

The *Status* register indicates a variety of conditions within the chip. Writing a '1' to a *Status* register bit will clear that bit if the condition that set it has been removed. Writing a '0' to any bit has no effect.

The *Mask* register is used to control the activation of the INT pin. Writing a '1' to a *Mask* register bit will allow the corresponding *Status* register bit to activate the INT pin when set.

DRDY	Data Ready. During conversion, this bit indicates that low-rate results have been updated. It indicates completion of other commands and the reset sequence.
110R (120R)	Current Out of Range. Set when the measured current would cause the <i>I1</i> (<i>I2</i>) register to overflow.
V1OR (V2OR)	Voltage Out of Range. Set when the measured voltage would cause the $V1$ ($V2$) register to overflow.
CRDY	Conversion Ready. Indicates that sample rate (output word rate) results have been updated.
I1ROR (I2ROR)	RMS Current Out of Range. Set when RMS current would cause the $I1_{RMS}$ ($I2_{RMS}$) register to overflow.
V1ROR (V2ROR)	RMS Voltage Out of Range. Set when RMS voltage would cause the $V1_{RMS}$ ($V2_{RMS}$) register to overflow.
E1OR (E2OR)	Energy Out of Range. Set when average power would cause $P1_{AVG}$ ($P2_{AVG}$) to overflow.
I1FAULT (I2FAUL	T)Indicates when a current fault condition has occurred.
V1SAG (V2SAG)	Indicates when a voltage sag condition has occurred.
TUP	Indicates when the Temperature register (T) has been updated.
V1OD (V2OD)	Modulator oscillation has been detected in the voltage1 (voltage2) A/D.
110D (120D)	Modulator oscillation has been detected in the current1 (current2) A/D.
LSD	Low Supply Detect. Set when the voltage on the PFMON pin falls below the specified low level. The LSD bit cannot be reset until the voltage rises above the specified high level.
FUP	Frequency Updated. Indicates the Epsilon register has been updated.
ĪĊ	Invalid Command. Normally logic 1. Set to 0 when an invalid command is received. It may also indicate loss of serial command synchronization and the part may need to be re-ini-tialized.

8.2.13 Control (Ctrl) – Address: 28

23	22	21	20	19	18	17	16
PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0
15	14	13	12	11	10	9	8
-	-	-	l2gain	-	-	-	STOP
7	6	5	4	3	2	1	0
-	-	l1gain	INTOD	-	NOCPU	NOOSC	-
Default = PC[7:0]	Pha				ay in voltage re ample (OWR) i		nt. Phase is
I1gain (I	2gain) Sets 0 =	s the gain of th Gain is set for	e current1 (cu ±250mV rang ±50mV range	rrent2) input. e.			
STOP	0 =	minates E ² PR No Action Stop E ² PROM	OM command I Commands.	sequence (if u	sed).		
INTOD	0 =	overts INT outp Normal Outpu Open-drain O		ben drain outpu	ıt.		
NOCPU	0 =	res power by d CPUCLK Ena CPUCLK Disa		PUCLK output	pin.		
NOOSC	0 =	ables the cryst Crystal Oscilla Crystal Oscilla		aking XIN a lo	gic-level input.		



8.3 Page 1 Registers

8.3.1 DC Offset for Current ($I1_{OFF}$, $I2_{OFF}$) and Voltage ($V1_{OFF}$, $V2_{OFF}$) Address: 0 ($I1_{OFF}$), 2 ($V1_{OFF}$), 7 ($I2_{OFF}$), 9 ($V2_{OFF}$)

MSB														LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	 2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

Default = 0

DC offset registers $I1_{OFF}$ & $V1_{OFF}$ ($I2_{OFF}$ & $V2_{OFF}$) are initialized to zero on reset. During DC offset calibration, selected registers are written with the inverse of the DC offset measured. The application program can also write the DC offset register values. These are two's complement values in the range of -1.0 \leq value < 1.0, with the binary point to the right of the MSB.

^{8.3.2} Gain for Current ($I1_{GAIN}$, $I2_{GAIN}$) and Voltage ($V1_{GAIN}$, $V2_{GAIN}$) Address: 1 ($I1_{GAIN}$), 3 ($V1_{GAIN}$), 8 ($I2_{GAIN}$), 10 ($V2_{GAIN}$)

MSB														LSB
2 ¹	2 ⁰	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	 2 ⁻¹⁶	2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²

Default = 1.0

Gain registers $I1_{GAIN}$ & $V1_{GAIN}$ ($I2_{GAIN}$ & $V2_{GAIN}$) are initialized to 1.0 on reset. During AC or DC gain calibration, selected register are written with the multiplicative inverse of the gain measured. These are unsigned fixed-point values in the range of $0 \le$ value < 4.0, with the binary point to the right of the second MSB.

8.3.3 Power Offset (P1_{OFF}, P2_{OFF}) Address: 4 (P1_{OFF}), 11 (P2_{OFF})

MSB														LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	 2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

Default = 0

Power offset $P1_{OFF}(P2_{OFF})$ is added to instantaneous power and averaged over a low-rate interval to yield $P1_{AVG}(P2_{AVG})$ register results. It can be used to reduce systematic energy errors. These are two's complement values in the range of -1.0 \leq value < 1.0, with the binary point to the right of the MSB.

8.3.4 AC Offset for Current (I1_{ACOFF}, I2_{ACOFF}) and Voltage (V1_{ACOFF}, V2_{ACOFF}) Address: 5 (I1_{ACOFF}), 6 (V1_{ACOFF}), 12 (I2_{ACOFF}), 13 (V2_{ACOFF})

MSB								_							LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷		2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

Default = 0

AC offset registers $I1_{ACOFF} \& V1_{ACOFF} (V_{ACOFF} \& V2_{ACOFF})$ are initialized to zero on reset. These are added to the RMS results before being stored to the RMS result registers. They can be used to reduce systematic errors in the RMS results. These are two's complement values in the range of $-1.0 \le$ value < 1.0, with the binary point to the right of the MSB.

8.3.5 Mode Control (Modes) – Address: 16

23	22	21	20	19	18	17	16			
-	VFIX	-	-	-	-	-	-			
15	14	13	12	11	10	9	8			
-	E1MODE1	E1MODE0	-	-	E2MODE1	E2MODE0	VHPF2			
7	6	5	4	3	2	1	0			
IHPF2	VHPF1	IHPF1	-	E3MODE1	E3MODE0	POS	AFC			
Default	= 0									
VFIX	0 =	internal RMS v Use voltage inp Use internal RM	but.			average active p	oower.			
E1MOD	00 = 01 = 10 =	$\overline{E2}, and \overline{E3} alt = \underline{E1}, \underline{E2} = P1_A = \underline{E1}, \underline{E2} = S1, = \underline{E1}, \underline{E2} = Q1_A = \underline{E1}, \underline{E1} = \underline{E1}, \underline{E2} = Q1_A = \underline{E1}, \underline{E1} = \underline{E1}, $	N_{VG} , $P2_{AVG}$ S2 N_{VG} , $Q2_{AVG}$	mode (when e	nabled by E2M	10DE).				
E2MOD	00 = 01 = 10 =	Output Mode = Energy Sign = Total Appare = Not Used = Enable E1M0								
VHPF2:	00 = 01 = 10 =	h-pass Filter Ei = No Filter = HPF on Curr = HPF on Volta = HPF on both	ent, PMF on V age, PMF on C	/oltage Current						
VHPF1:	00 = 01 = 10 =	h-pass Filter Ei = No Filter = HPF on Curr = HPF on Volta = HPF on both	ent, PMF on V age, PMF on C	/oltage Current						
E3MOD	00 = 01 = 10 =	E3 Output Mode (with E1MODE disabled) 00 = Total Reactive Energy (default) 01 = Power Fail Monitor 10 = Voltage1 Sign 11 = Total Apparent Energy								
E3MOD	00 = 01 = 10 =	Output Mode (\ = Power Fail M = Energy Sign = Not Used = Not Used		enabled)						
POS		itive Energy Or alculated, zero			ues in P1 _{AVG} a	nd <i>P</i> 2 _{AVG} . If a n	egative value			
AFC	frec		ement comple	etes. <i>Epsilon</i> is	used to contro	<i>psilon</i> every tin of the gain of th				



8.3.6 Line to Sample Frequency Ratio (Epsilon) – Address: 17

MSB														LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	 2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

Default = 0.0125 (4.0 kHz x 0.0125 or 50 Hz)

Epsilon is the ratio of the input line frequency to the output word rate (OWR). It can either be written by the application program or calculated automatically from the line frequency (from the voltage input) using the AFC bit in the *Modes* register. It is a two's complement value in the range of $-1.0 \le$ value < 1.0, with the binary point to the right of the MSB. Negative values are not used.

8.3.7 Pulse Output Width (PulseWidth) – Address: 14

MSB								 _						LSB
0	2 ²²	2 ²¹	2 ²⁰	2 ¹⁹	2 ¹⁸	2 ¹⁷	2 ¹⁶	 2 ⁶	2 ⁵	2 ⁴	2 ³	2 ²	2 ¹	2 ⁰

Default = 1 (250 uS at OWR = 4 kHz)

PulseWidth sets the duration of energy pulses. The actual pulse duration is the contents of PulseWidth divided by the output word rate (OWR). PulseWidth is an integer in the range of 1 to 8,388,607.

8.3.8 Pulse Output Rate (PulseRate) – Address: 15

MSB							_	 _						LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	 2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

Default= -1

PulseRate sets the full-scale frequency for $\overline{E1}$, $\overline{E2}$, $\overline{E3}$ pulse outputs. For a 4 kHz sample rate, the maximum pulse rate is 2 kHz. This is a two's complement value in the range of $-1 \le value < 1$, with the binary point to the left of the MSB.

Refer to 6.10 Energy Pulse Rate on page 21 for more information.

8.3.9 Cycle Count (N) – Address: 19

MSB														LSB
0	2 ²²	2 ²¹	2 ²⁰	2 ¹⁹	2 ¹⁸	2 ¹⁷	2 ¹⁶	 2 ⁶	2 ⁵	2 ⁴	2 ³	2 ²	2 ¹	2 ⁰

Default = 4000

Determines the number of output word rate (OWR) samples to use in calculating low-rate results. Cycle Count (N) is an integer in the range of 10 to 8,388,607. Values less than 10 should not be used.

Address: 20 (Q1_{WB}), 21 (Q2_{WB})

MSB														LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	 2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

Wideband reactive power is calculated using vector subtraction. (See Section 4.8 Power and Energy Results on page 16). The value is signed, but has a range of $0 \le value < 1.0$. The binary point is to the right of the MSB.

^{8.3.10} Wideband Reactive Power (Q1_{WB}, Q2_{WB})



8.3.11 Temperature Gain (T_{GAIN}) – Address: 22

MSB								 _						LSB	
2 ⁶	2 ⁵	2 ⁴	2 ³	2 ²	2 ¹	2 ⁰	2 ⁻¹	 2 ⁻¹¹	2 ⁻¹²	2 ⁻¹³	2 ⁻¹⁴	2 ⁻¹⁵	2 ⁻¹⁶	2 ⁻¹⁷	

Default = 0x2F02C3

Refer to 6.13 *Temperature Measurement* on page 22 for more information.

8.3.12 Temperature Offset (T_{OFF}) – Address: 23

MSB														LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	 2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

Default = 0xF3D35A

Refer to 6.13 *Temperature Measurement* on page 22 for more information.

8.3.13 Filter Settling Time for Conversion Startup (T_{SETTLE}) – Address: 25

MSB														LSB
2 ²³	2 ²²	2 ²¹	2 ²⁰	2 ¹⁹	2 ¹⁸	2 ¹⁷	2 ¹⁶	 2 ⁶	2 ⁵	2 ⁴	2 ³	2 ²	2 ¹	2 ⁰

Default = 30

Sets the number of output word rate (OWR) samples that will be used to allow filters to settle at the beginning of Conversion and Calibration commands. This is an integer in the range of 0 to 8,388,607 samples.

8.3.14 No Load Threshold (Load_{MIN}) – Address: 26

MSB														LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	 2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

Default = 0

 $Load_{MIN}$ is used to set the no load threshold. When the magnitude of the E_{PULSE} register is less than $Load_{MIN}$, E_{PULSE} will be zeroed. If the magnitude of the Q_{PULSE} register is less than $Load_{MIN}$, Q_{pulse} will be zeroed. Load_{MIN} is a two's compliment value in the range of -1.0 \leq value < 1.0, with the binary point to the right of the MSB. Negative values are not used.

8.3.15 Voltage Fixed RMS Reference (VF_{RMS}) – Address 27

MSB														LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷	 2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

Default = 0.7071068 (full scale RMS)

If the application program detects that the meter has possibly been tampered with in such a manner that the voltage input is no longer working, it may choose to use this internal RMS reference instead of the disabled voltage input by setting the VFIX bit in the *Modes* register. This is a two's complement value in the range of $0 \le$ value < 1.0, with the binary point to the right of the MSB. Negative values are not used.



8.3.16 System Gain (G) – Address: 28

MSR

MSB														LSB
-(2 ¹)	2 ⁰	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	 2 ⁻¹⁶	2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²

Default = 1.25

System Gain (G) is applied to all channels. By default, G = 1.25, but can be finely adjusted to compensate for voltage reference error. It is a two's complement value in the range of $-2.0 \le$ value < 2.0, with the binary point to the right of the second MSB. Values should be kept within 5% of 1.25.

8.3.17 System Time (Time) – Address: 29

MSB														LSB
2 ²³	2 ²²	2 ²¹	2 ²⁰	2 ¹⁹	2 ¹⁸	2 ¹⁷	2 ¹⁶	 2 ⁶	2 ⁵	2 ⁴	2 ³	2 ²	2 ¹	2 ⁰

Default = 0

System Time (Time) is measured in output word rate (OWR) samples. This is an unsigned integer in the range of 0 to 16,777,215 samples. At OWR = 4.0 kHz, OWR will overflow every 1 hour, 9 minutes, and 54 seconds. *Time* can be used by the application to manage real-time events.



8.4 Page 2 Registers

8.4.1 Voltage Sag and Current Fault Duration (V1Sag_{DUR}, V2Sag_{DUR}, I1Fault_{DUR}, I2Fault_{DUR}) Address: 0 (V1Sag_{DUR}), 8 (V2Sag_{DUR}), 4 (I1Fault_{DUR}), 12 (I2Fault_{DUR})

MSB														LSB
0	2 ²²	2 ²¹	2 ²⁰	2 ¹⁹	2 ¹⁸	2 ¹⁷	2 ¹⁶	 2 ⁶	2 ⁵	2 ⁴	2 ³	2 ²	2 ¹	2 ⁰

Default = 0

Voltage sag duration, $V1Sag_{DUR}$ ($V2Sag_{DUR}$) and current fault duration, $I1Fault_{DUR}$ ($I2Fault_{DUR}$) determine the count of output word rate (OWR) samples utilized to determine a sag or fault event. These are integers in the range of 0 to 8,388,607 samples. A value of zero disables the feature.

8.4.2 Voltage Sag and Current Fault Level (V1Sag_{LEVEL}, V2Sag_{LEVEL}, I1Fault_{LEVEL}, I2Fault_{LEVEL}), Address: 1 (V1Sag_{LEVEL}), 9 (V2Sag_{LEVEL}), 5 (I1Fault_{LEVEL}), 13 (I2Fault_{LEVEL})

MSB								_							LSB
-(2 ⁰)	2 ⁻¹	2 ⁻²	2 ⁻³	2 ⁻⁴	2 ⁻⁵	2 ⁻⁶	2 ⁻⁷		2 ⁻¹⁷	2 ⁻¹⁸	2 ⁻¹⁹	2 ⁻²⁰	2 ⁻²¹	2 ⁻²²	2 ⁻²³

Default = 0

Voltage sag level, $V1Sag_{LEVEL}$ ($V2Sag_{LEVEL}$) and current fault level, $I1Fault_{LEVEL}$ ($I2Fault_{LEVEL}$) establish an input level below which a sag or fault is triggered. These are two's complement values in the range of $-1.0 \le$ value < 1.0, with the binary point to the right of the MSB. Negative values are not used.

8.5 Page 5 Register

8.5.1 Temperature Measurement (T_{MFAS}) – Address: 26

MSB														LSB
2 ²³	2 ²²	2 ²¹	2 ²⁰	2 ¹⁹	2 ¹⁸	2 ¹⁷	2 ¹⁶	 2 ⁶	2 ⁵	2 ⁴	2 ³	2 ²	2 ¹	2 ⁰

Default = 0

The Temperature Measurement (T_{MEAS}) register is used to cycle-steal voltage channel2 for temperature measurement. Writing a one to the LSB causes the temperature to be measured and the Temperature register (*T*) to be updated.

Refer to 6.13 *Temperature Measurement* on page 22 for more information.



9. SYSTEM CALIBRATION

9.1 Calibration

The CS5467 provides DC offset and gain calibration that can be applied to the voltage and current measurements, and AC offset calibration which can be applied to the voltage and current RMS calculations.

Since the voltage and current channels have independent offset and gain registers, offset and gain calibration can be performed on any channel independently.

The data flow of the calibration is shown in Figure 10.

The CS5467 must be operating in its active state and ready to accept valid commands. Refer to 7.6 *Commands* on page 25.

The value in the Cycle Count register (*N*) determines the number of output word rate (OWR) samples that are averaged during a calibration. DC offset and gain calibrations take at least $N + T_{SETTLE}$ samples. AC offset calibrations take at least $6(N) + T_{SETTLE}$ samples. As *N* is increased, the accuracy of calibration results tends to also increase.

The DRDY bit in the *Status* register will be set at the completion of Calibration commands. If an overflow occurs during calibration, other *Status* register bits may be set as well.

9.1.1 Offset Calibration

During offset calibrations, no line voltage or current should be applied to the meter. A zero-volt differential signal can also be applied to the voltage inputs VIN1 \pm (VIN2 \pm) or current inputs IIN1 \pm (IIN2 \pm) of the CS5467. (see Figure 11.)

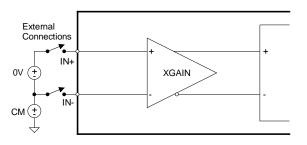


Figure 11. System Calibration of Offset

9.1.1.1 DC Offset Calibration

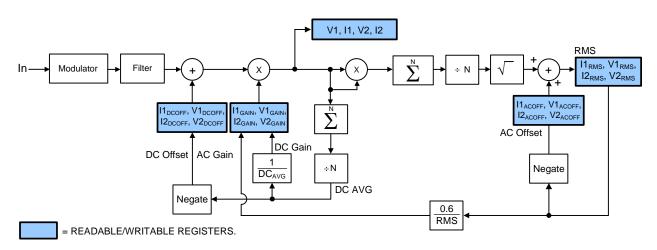
The DC Offset Calibration command measures and averages DC values read on specified voltage or current channels at zero input and stores the inverse result in the associated offset registers. This will be added to instantaneous measurements in subsequent conversions, removing the offset.

Gain registers for channels being calibrated should be set to 1.0 prior to performing DC offset calibration.

9.1.1.2 AC Offset Calibration

The AC Offset Calibration command measures the residual RMS values read on specified voltage or current channels at zero input and stores the inverse result in the associated AC offset registers. This will be added to RMS measurements in subsequent conversions, removing the offset.

AC offset registers for channels being calibrated should first be cleared prior to performing the calibration.





9.1.2 Gain Calibration

During gain calibration, a full-scale reference signal must be applied to the meter or optionally, scaled to the VIN1 \pm (VIN2 \pm), IIN1 \pm (IIN2 \pm) pins of the CS5467. A DC reference must be used for DC gain calibration. Either an AC or DC reference can be used for RMS AC calibrations. If DC is used, the associated high-pass filter (HPF) must be off.

Figure 12 shows the basic setup for gain calibration.

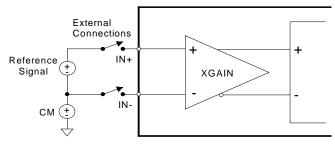


Figure 12. System Calibration of Gain.

Using a reference that is too large or too small can cause an over-range condition during calibration. Either condition can set *Status* register bits I1OR (I2OR) V1OR (V2OR) for DC and I1ROR (I2ROR) V1ROR (V2ROR) for AC calibration.

Full scale (FS) for the voltage input is $\pm 250 \text{ mV}$ peak and for the current inputs is $\pm 250 \text{ mV}$ or $\pm 50 \text{ mV}$ peak depending on selected gain range. The normal peak voltage applied to these pins should not exceed these levels during calibration or normal operation.

The range of the gain registers limits the gain calibration range and subsequently the range of the reference level that can be applied. The reference should not exceed FS or be lower than FS/4.

9.1.2.1 AC Gain Calibration

Full scale for AC RMS gain calibrations is 60% of the input's full-scale range, which is either 250 mV or 50 mV depending on the gain range selected. That's 150 mV or 30 mV, again depending on range. So the normal reference input level should be either 150 or 30 mV_{RMS}, AC or DC.

Prior to executing an AC Gain Calibration command, gain registers for any channel to be calibrated should be set to 1.0 if the reference level mentioned above is used, or to that level divided by the actual reference level used. During AC gain calibration the RMS level of the applied reference is measured with the preset gain, then divided into 0.6 and the quotient stored back into the corresponding gain register.

9.1.2.2 DC Gain Calibration

With a DC reference applied, the DC Gain Calibration command measures and averages DC values read on the specified voltage or current channels and stores the reciprocal result in the associated gain registers, converting measured voltage into needed gain. Subsequent conversions will use the new gain value.

9.1.3 Calibration Order

- 1. DC offset.
- 2. DC or AC gain.
- 3. AC offset (if needed).

If both AC gain and offset calibrations were performed, it is possible to repeat both to obtain additional accuracy as AC gain and offset may interact.

9.1.4 Temperature Sensor Calibration

Temperature sensor calibration involves the adjustment of two parameters - Δ VBE and VBE0. These values must be known in order to calibrate the temperature sensor. See Section 6.13 *Temperature Measurement* on page 22 for an explanation of Δ VBE and VBE0 and how to calculate T_{GAIN} and T_{OFF} register values from them.

9.1.4.1 Temperature Offset Calibration

Offset calibration can be done at any temperature, but should be done mid-scale if any gain error exists.

Subtract the measured *T* register temperature from the actual temperature to determine the offset error. Multiply this error by Δ VBE and add it to VBE0 to yield a new VBE0 value. Recalculate *T*_{OFF} using this new value.

9.1.4.2 Temperature Gain Calibration

Two temperature points far enough apart to give reasonable accuracy, for example 25°C and 85°C, are required to calibrate temperature gain.

Divide the actual temperature difference by the measured (*T* register) difference for the two temperatures. This gives a gain correction factor. Update the T_{GAIN} register by multiplying it's value by this correction factor.

Update ΔVBE by dividing its old value by the gain correction factor. It will be needed for subsequent offset calibrations.



10. E²PROM OPERATION

The CS5467 can accept commands from a serial E^2 PROM connected to the serial interface instead of a host microcontroller. A high level (logic 1) on the MODE input indicates that an E^2 PROM is connected. This makes the \overline{CS} and SCLK pins become driven outputs. After reset and after running the initialization program, the CS5467 begins reading commands from the connected E^2 PROM.

10.1 E²PROM Configuration

A typical connection between the CS5467 and a E^2 PROM is shown in Figure 13.

The CS5467 asserts \overline{CS} (logic 0), clocks SCLK, and sends Read commands to the E²PROM on SDO.

Command format is identical to microcontroller mode, except the CS5467 will not attempt to write to the EE-PROM device. The command sequence stops when the STOP bit in the Control register (*Ctrl*) is written by the command sequence.

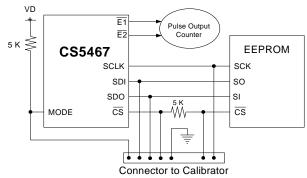


Figure 13. Typical Interface of E²PROM to CS5467

Figure 13 also shows the external connections that would be made to a calibration device, such as a notebook computer, handheld calibrator, or tester during meter assembly, The calibrator or tester can be used to control the CS5467 during calibration and program the required values into the E^2 PROM.

10.2 E²PROM Code

The EEPROM code should do the following:

- 1. Set any Configuration or Control register bits, such as HPF enables and phase compensation settings.
- 2. Write any calibration data to gain and offset registers.
- 3. Set energy output pulse width, rate, and formats.
- 4. Execute a Continuous Conversion command.
- 5. Set the STOP bit in the Control register (last).

Below is an example E²PROM code set.

- -7E 00 00 01
- Change to page 1.
- -60 00 01 E0
- Write *Modes* Register, turn high-pass filters on. -42 7F C4 A9
- Write value of 0x7FC4A9 to *I1_{GAIN}* register. -46 FF B2 53
- Write value of 0xFFB253 to $V1_{GAIN}$ register.
- -50 7F C4 A9
- Write value of 0x7FC4A9 to $I2_{GAIN}$ register.
- -54 FF B2 53
- Write value of 0xFFB253 to V2_{GAIN} register.
- -7E 00 00 00
 - Change to page 0.
- -74 00 00 04
- Set LSD bit to 1 in the *Mask* register.
- -E8

Start continuous conversions

-78 00 01 00

Write STOP bit to the Control register (*Ctrl*) to terminate E^2 PROM command sequence.

10.3 Which E²PROMs Can Be Used?

Several industry-standard serial E²PROMs can be used with the CS5467. Some are listed below:

- Atmel AT25010, AT25020 or AT25040
- National Semiconductor NM25C040M8 or NM25020M8
- Xicor X25040SI

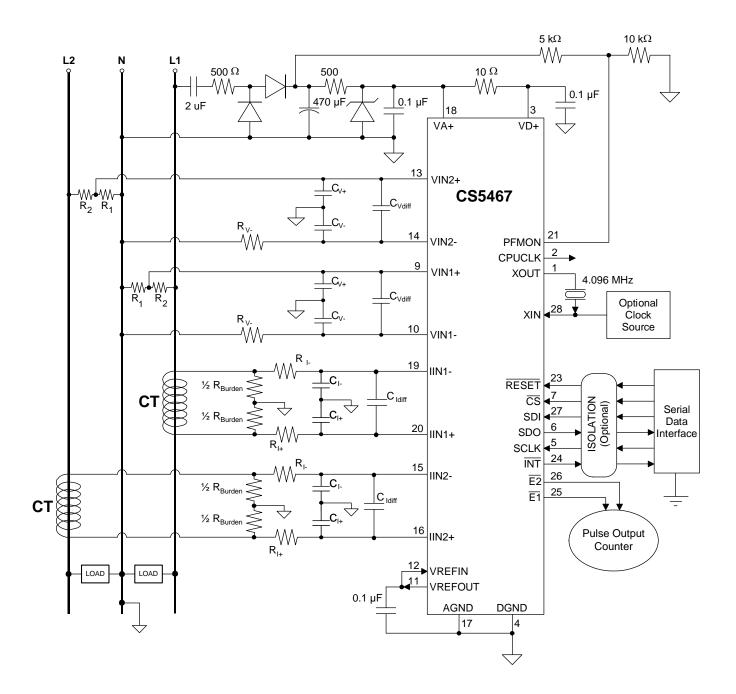
These serial E^2 PROMs expect a specific 8-bit command (00000011) in order to perform a memory read. The CS5467 has been hardware programmed to transmit this 8-bit command to the E^2 PROM after reset.



11. BASIC APPLICATION CIRCUITS

Figure 14 shows the CS5467 configured to measure power in a single-phase, 3-wire system while operating in a single-supply configuration. In this diagram, current

transformers (CT) are used to sense the line currents and voltage dividers are used to sense the line voltages.

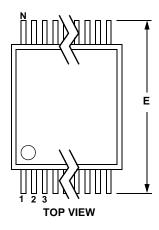


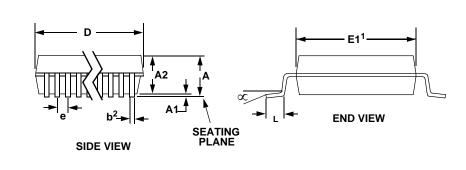




12. PACKAGE DIMENSIONS

28L SSOP PACKAGE DRAWING





		INCHES			MILLIMETERS		NOTE
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
A			0.084			2.13	
A1	0.002	0.006	0.010	0.05	0.15	0.25	
A2	0.064	0.069	0.074	1.62	1.75	1.88	
b	0.009		0.015	0.22		0.38	2,3
D	0.390	0.4015	0.413	9.90	10.20	10.50	1
E	0.291	0.307	0.323	7.40	7.80	8.20	
E1	0.197	0.209	0.220	5.00	5.30	5.60	1
е	0.022	0.026	0.030	0.55	0.65	0.75	
L	0.025	0.0354	0.041	0.63	0.90	1.03	
x	0°	4°	8°	0°	4°	8°	

JEDEC #: MO-150

Controlling Dimension is Millimeters

- Notes: 1. "D" and "E1" are reference datums and do not included mold flash or protrusions, but do include mold mismatch and are measured at the parting line, mold flash or protrusions shall not exceed 0.20 mm per side.
 - 2. Dimension "b" does not include dambar protrusion/intrusion. Allowable dambar protrusion shall be 0.13 mm total in excess of "b" dimension at maximum material condition. Dambar intrusion shall not reduce dimension "b" by more than 0.07 mm at least material condition.
 - 3. These dimensions apply to the flat section of the lead between 0.10 and 0.25 mm from lead tips.



13. ORDERING INFORMATION

Model	Temperature	Package
CS5467-ISZ (lead free)	-40 to +85 °C	28-pin SSOP

14. ENVIRONMENTAL, MANUFACTURING, & HANDLING INFORMATION

Model Number	Peak Reflow Temp	MSL Rating*	Max Floor Life
CS5467-ISZ (lead free)	260 °C	3	7 Days

* MSL (Moisture Sensitivity Level) as specified by IPC/JEDEC J-STD-020.

15. REVISION HISTORY

Revision	Date	Changes
PP1	FEB 2007	Initial release.
PP2	FEB 2007	Corrections to implicitly state that temperature measurement is a secondary function of voltage2 channel. Updated typical connection diagram. Changed Phase Compensation Range from $\pm 2.8^{\circ}$ to $\pm 5.4^{\circ}$.
F1	MAR 2007	Updated to F1 for quality process level (QPL).
F2	JAN 2010	Increased on-chip reference temperature coefficient from 25 ppm / °C typ. to 40 ppm / °C typ.
F3	APR 2011	Removed lead-containing (Pb) device ordering information.

Contacting Cirrus Logic Support

For all product questions and inquiries contact a Cirrus Logic Sales Representative.

To find the one nearest to you go to www.cirrus.com

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